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2025

2025 GLASS SUBSTRATE TGV INDUSTRY CHAIN SUMMIT FORUM

March 19th to 20th, 2025
Suzhou · Jiangsu

1. Background

Glass Substrate: The Next Generation Chip Substrate

Glass substrate, crafted from core glass material, is poised to redefine the chip substrate industry. This industry chain spans production, raw materials, equipment, technology, packaging, testing, and application segments, with production, raw materials, and equipment forming the upstream components.

Due to its distinctive physical and chemical properties, glass substrates are demonstrating significant potential in the realm of electronic component materials.

Industry Leaders Embrace Glass Substrates

In an effort to extend the boundaries of Moore's Law, major manufacturers such as Intel, Samsung, NVIDIA, and TSMC have ventured into the glass substrate industry. Intel pioneered the use of glass substrates for advanced packaging, furthering the progression of Moore's Law. Samsung envisions glass substrates as the future of chip packaging and has significantly ramped up its research and development efforts. NVIDIA's GB200 is expected to incorporate glass substrates and is gearing up for production. Meanwhile, TSMC has established a specialized team to delve into FOPLP technology and has made substantial investments in glass substrate research and development.

Innovative Technology: Through-Glass Via (TGV)

TGV interconnection technology, which originated in 2008, evolved from 2.5D/3D integrated TSV adapter board technology. Its primary aim is to address the challenges associated with silicon substrates, such as substrate loss, high material costs, and complex processing

requirements. This technology has seen significant improvements in recent years. Various leading companies are now producing prototypes for diverse applications including sensors, CPUs, GPUs, AI, display panels, medical devices, and advanced semiconductor packaging.

Market Growth and Projections

The global IC packaging substrate market is rapidly expanding and is projected to reach US$31.54 billion by 2029. Glass substrates, as the latest innovation, are expected to achieve a market penetration rate of over 50% within the next five years. The global glass substrate market is anticipated to grow to US$11.3 billion by 2031. In China, the market for glass substrates continued to expand, reaching 33.3 billion yuan in 2023. Corning dominates the global market, accounting for 48% of it. Domestic manufacturers have significant cost advantages, and the localization of glass substrates has accelerated, presenting vast market opportunities. The corporate strategy surrounding TGV is set to intensify in the latter half of 2024.

Upcoming Event: Glass Substrate TGV Industry Chain Summit Forum

To further promote the development of this burgeoning industry, Aibang will host the Glass Substrate TGV Industry Chain Summit Forum in Suzhou from March 19th to 20th, 2025. This conference will assemble leading experts, scholars, and corporate representatives to explore future trends, technological innovations, and market opportunities within the glass substrate sector.

Organizers: Shenzhen Aibang Intelligent Manufacturing Information Co., Ltd.

Website: www.ab-sm.com

2. Agenda (TBD)

NO.	Topic	Companies to be invited
1	Challenges and solutions of TGV glass core technology	Guangdong Fozhixin Microelectronics Technology Research Co., LTD
2	Difficulties in the production of TGV metal lines and their technical solutions	Hubei TGVTECH Co., Ltd.
3	Glass core substrate: a new generation of advanced packaging technology	AKM Meadville Electronics (Xiamen) Co. Ltd.
4	The latest generation of TGV technology and applications	3D CHIPS (GUANGDONG) TECHNOLOGYCO.,LTD
5	SCHOTT glass enables advanced packaging	SCHOTT Group
6	Application of microscope in semiconductor advanced packaging defect detection	Guangdong Huipuguangxue Technology Co., Ltd.
7	Prospects for the application of through-glass technology in advanced packaging	Xiamen Sky Semiconductor Technology Co.Ltd.
8	Discussion on the filling technology of through-hole in glass substrate	Guangdong Tiancheng Technology Co., Ltd.
9	Laser-induced deep etching technology is used to realize the processing of glass substrates with integrated multi-functional structures	LPKF China
10	Design, development and application of high-performance IPD based on TGV	ShangHai Xpeedic Co., Ltd.
11	Application of Multi-physics Simulation Technology in Glass-based Advanced Packaging	Hunan More Than Moore Advanced Semiconductor Co.,Ltd.
12	High-density glass-level packaging and heterogeneous integration process development challenges and solutions	Chengdu ECHINT Technology Co., Ltd.
13	Application of PVD equipment in deep hole coating in TGV technology	Guangdong Huicheng Vacuum Technology Co., Ltd.
14	From round to square: Evatec's advanced packaging substrate FOPLP etching and sputtering solutions	Evatec China
15	The latest progress and future prospects of glass substrate packaging technology	Shenzhen Fanxin Integrated Semiconductor Co., Ltd.
16	Innovative technologies and applications of glass substrates: from plasma vias to surface modification and metal seed layer technology	UVAT Technology co.,Ltd.
17	Panel level laser induced etching & AOI	Shenzhen GH LASER Co., Ltd.

NO.	Topic	Companies to be invited
18	Integrated passive on glass substrate	SUzhou senwan Electronic Technology Co., Ltd.
19	TBD	Hangzhou MDK Opto Electronics Co., Ltd
20	FLEE-TGV promotes the development of advanced packaging glass substrates	Han's Laser Technology Industry Group Co., Ltd

3.Feedback Channel:

The final agenda and list of speakers will be updated in the near future and on the day of the conference. If you are interested in participating as a speaker or exhibitor at the 2025 TGV Forum, or if you are interested in opportunities for sponsorship, advertising, article submissions, conducting interviews, or if you have leading technology or product solutions, please contact Rongrong via email at lirongrong@aibang.com, Additional contact number: +8618823755657, or add Rongrong on WeChat: *aibang360040*. You can also click the following link to view the latest information: https://www.ab-sm.com/a/63204.